2826

Attorney's Docket No.: 42P12752 Patent

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:	Scot A. Kellar et al.	Examiner:	Williams, Alexander O.
U.S. Serial No:	10/066,643	Art Unit:	2826
Filed:	February 6, 2002		
For:	WAFER BONDING FOR 3-D INTEGRATION		

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO ELECTION REQUIREMENT

Sir:

In response to the Election Requirement mailed October 1, 2003, applicant(s) hereby elects to prosecute Group I claims, claims 1-7 and 15-20 drawn to a three-dimensional (3-D) integrated chip system. As such, applicant(s) elects to withdraw Group II claims 8-14 drawn to making a wafer bonding method.

If there are any additional charges, please charge Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN

Date: 10/27/03

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